

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

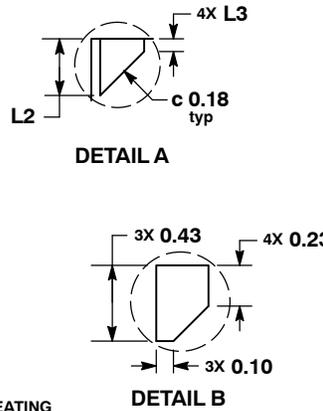
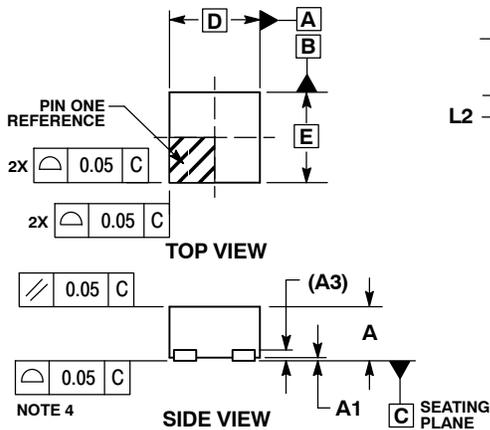
ON Semiconductor®



SCALE 4:1

UDFN4 1.0x1.0, 0.65P
CASE 517BR-01
ISSUE O

DATE 27 OCT 2010

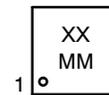


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

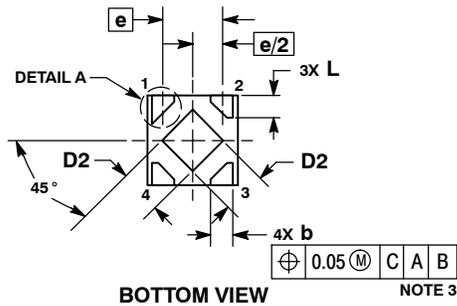
| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | --- | 0.60 |
| A1 | 0.00 | 0.05 |
| A3 | 0.10 | REF |
| b | 0.20 | 0.30 |
| D | 1.00 | BSC |
| D2 | 0.43 | 0.53 |
| E | 1.00 | BSC |
| e | 0.65 | BSC |
| L | 0.20 | 0.30 |
| L2 | 0.27 | 0.37 |
| L3 | 0.02 | 0.12 |

GENERIC MARKING DIAGRAM*

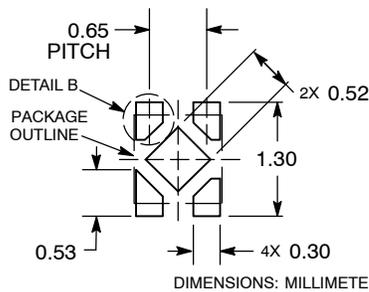


XX = Specific Device Code
MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | UDFN4, 1.0X1.0, 0.65P | PAGE 1 OF 2 |

